

METHOD AND APPARATUS FOR REMOVING A TARGET LAYER FROM A SUBSTRATE USING REACTIVE GASES

ABSTRACT OF THE DISCLOSURE

A system and method for removing a layer from a substrate surface is provided. The method includes providing at least one encapsulating transport, where the encapsulating transport contains at least some reactive gas. At least one encapsulating transport is applied to the layer, and the layer is a chemically reactive layer. The encapsulating transport ruptures on the chemically reactive layer and releases the reactive gas in combination with a reaction inducing agent onto the chemically reactive layer to facilitate removal of the layer from the substrate surface.